INTERCONNECTS FOR PACKAGED SEMICONDUCTOR DEVICES AND METHODS FOR MANUFACTURING SUCH DEVICES

ABSTRACT

Packaged semiconductor devices and assemblies including interconnects and methods for forming such interconnects are disclosed herein. One embodiment of a packaged semiconductor assembly includes a die attached to a support layer. A plurality of interconnects are embedded in and project from the support layer, such that the support layer at least partially retains the interconnects in a predetermined array. An encapsulant is molded around each of the interconnects and encases at least a portion of the die, support layer and interconnects.

Fig. 2